OPA846-DIE Wideband, Low-Noise, Voltage-Feedback Operational Amplifier

1 Features

- High Bandwidth
- Low-Input Voltage Noise
- Very Low Distortion
- High-Slew Rate
- High DC Accuracy
- Low-Supply Current
- High-Gain Bandwidth Product

2 Applications

- High-Dynamic Range ADC Preamps
- Low-Noise, Wideband, Transimpedance Amplifiers
- Wideband, High-Gain Amplifiers
- Low-Noise Differential Receivers
- VDSL Line Receivers
- Ultrasound Channel Amplifiers
- Security Sensor Front Ends

3 Description

The OPA846-DIE combines very-high-gain bandwidth and large signal performance with very-low-input voltage noise, while dissipating a low-supply current. The classical differential input stage, along with two stages of forward gain and a high-power output stage, combine to make the OPA846-DIE an exceptionally low-distortion amplifier with excellent DC accuracy and output drive. The voltage-feedback architecture allows all standard op amp applications to be implemented with very high performance.

The combination of low-input voltage and current noise, along with gain bandwidth, make the OPA846 an ideal amplifier for wideband transimpedance stages.

A new external compensation technique can be used to give a very flat frequency response below the minimum stable gain for the OPA846-DIE, further improving its already exceptional distortion performance.

4 Revision History

Changes from Original (December 2013) to Revision A

- Added designator to diagram in Bare Die Information section
- Added note after diagram in Bare Die Information section regarding added designator
- Changed description for pad number 5 and 6 in the Bond Pad Coordinates in Microns table

Ordering Information

<table>
<thead>
<tr>
<th>PRODUCT</th>
<th>PACKAGE DESIGNATOR</th>
<th>PACKAGE</th>
<th>ORDERABLE PART NUMBER</th>
<th>PACKAGE QUANTITY</th>
</tr>
</thead>
<tbody>
<tr>
<td>OPA846</td>
<td>TD</td>
<td>Bare die in waffle pack(2)</td>
<td>OPA846TDB1</td>
<td>300</td>
</tr>
<tr>
<td></td>
<td></td>
<td></td>
<td>OPA846TDB2</td>
<td>10</td>
</tr>
</tbody>
</table>

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

(2) Processing is per the Texas Instruments commercial production baseline and is in compliance with the Texas Instruments Quality Control System in effect at the time of manufacture. Electrical screening consists of DC parametric and functional testing at room temperature only. Unless otherwise specified by Texas Instruments, AC performance and performance over temperature is not warranted. Visual Inspection is performed in accordance with MIL-STD-883 Test Method 2010 Condition B at 75X minimum.

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This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

5  Bare Die Information

<table>
<thead>
<tr>
<th>DIE THICKNESS</th>
<th>BACKSIDE FINISH</th>
<th>BACKSIDE POTENTIAL</th>
<th>BOND PAD METALLIZATION COMPOSITION</th>
<th>BOND PAD THICKNESS</th>
</tr>
</thead>
<tbody>
<tr>
<td>10.5 mils.</td>
<td>Silicon with backgrind</td>
<td>Floating</td>
<td>Ti/AlCu (0.5%)/TiW</td>
<td>1010 nm</td>
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</table>

![Diagram of bond pad coordinates](image)

(1) Designator “CIC60140” may appear on die.

<table>
<thead>
<tr>
<th>DESCRIPTION</th>
<th>PAD NUMBER</th>
<th>X MIN</th>
<th>Y MIN</th>
<th>X MAX</th>
<th>Y MAX</th>
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</thead>
<tbody>
<tr>
<td>N/C</td>
<td>1</td>
<td>27</td>
<td>477</td>
<td>103</td>
<td>553</td>
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<tr>
<td>Inverting Input</td>
<td>2</td>
<td>27</td>
<td>251</td>
<td>105</td>
<td>329</td>
</tr>
<tr>
<td>Noninverting Input</td>
<td>3</td>
<td>27</td>
<td>27</td>
<td>103</td>
<td>103</td>
</tr>
<tr>
<td>Output</td>
<td>4</td>
<td>949</td>
<td>27</td>
<td>1025</td>
<td>103</td>
</tr>
<tr>
<td>–Vs</td>
<td>5</td>
<td>947</td>
<td>251</td>
<td>1025</td>
<td>329</td>
</tr>
<tr>
<td>+Vs</td>
<td>6</td>
<td>949</td>
<td>477</td>
<td>1025</td>
<td>553</td>
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</table>
### PACKAGING INFORMATION

<table>
<thead>
<tr>
<th>Orderable Device</th>
<th>Status (1)</th>
<th>Package Type</th>
<th>Package Drawing</th>
<th>Pins</th>
<th>Package Qty</th>
<th>Eco Plan (2)</th>
<th>Lead finish/ Ball material</th>
<th>MSL Peak Temp (3)</th>
<th>Op Temp (°C)</th>
<th>Device Marking (4/5)</th>
<th>Samples</th>
</tr>
</thead>
<tbody>
<tr>
<td>OPA846TDB1</td>
<td>ACTIVE</td>
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<td></td>
<td>0</td>
<td>300</td>
<td>RoHS &amp; Green</td>
<td>Call TI</td>
<td>N / A for Pkg Type</td>
<td>25 to 25</td>
<td></td>
<td></td>
</tr>
<tr>
<td>OPA846TDB2</td>
<td>ACTIVE</td>
<td></td>
<td></td>
<td>0</td>
<td>10</td>
<td>RoHS &amp; Green</td>
<td>Call TI</td>
<td>N / A for Pkg Type</td>
<td>25 to 25</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

(1) The marketing status values are defined as follows:
- **ACTIVE**: Product device recommended for new designs.
- **LIFEBUY**: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
- **NRND**: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
- **PREVIEW**: Device has been announced but is not in production. Samples may or may not be available.
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(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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